L Number	Hit	s Search Text		
-	2253		DB	Time stamp
			USPAT;	2003/04/12 1
			US-PGPUB EPO; JPO	
			DERWENT;	'
_			IBM TDB	
-	587	3 etching and recess and bonding	USPAT;	2003/04/11 10
	1		US-PGPUB	: 2003/04/11 1(
			EPO; JPO	
	ł		DERWENT;	
-	240	"MEMS" and (etching and recess and	IBM_TDB	
	1	bonding)	USPAT;	2003/04/11 11
	ĺ		US-PGPUB;	
	1		EPO; JPO;	
			DERWENT; IBM TDB	
_	1576	microsensors	USPAT;	2007/04/11 11
			US-PGPUB;	2003/04/11 11
			EPO; JPO;	
			DERWENT;	
.	5499	sporificial all t	IBM TDB	
ĺ	2400	sacrificial adj layer	USPAT;	2003/04/11 11
			US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
.	914	"MEMS" and (sacrificial adj layer)	IBM_TDB	
ļ		(Sacrificial adj layer)	USPAT;	2003/04/11 11:
		,	US-PGPUB;	
ĺ			EPO; JPO;	
ĺ			DERWENT;	
i	69		IBM_TDB	
ł		adj layer))	USPAT;	2003/04/11 11:
			US-PGPUB; EPO; JPO;	i
			DERWENT;	
	0.507	_	IBM TDB	
	2627	"MEMS" and mirror	USPAT;	2003/04/12 12
			US-PGPUB:	2003/04/12 10:
			EPO; JPO;	
1			DERWENT;	
ļ.	611590	cavity	IBM TDB	
,		cavity	USPAT;	2003/04/12 10:
ļ			US-PGPUB;	
ĺ			EPO; JPO;	
1			DERWENT;	
İ	744	("MEMS" and mirror) and cavity	IBM_TDB	
	i	and davicy	USPAT;	2003/04/12 10:3
	ľ		US-PGPUB;	
	ł		EPO; JPO; DERWENT;	1
	10070		IBM TDB	1
1	10978	substrate and sacrificial	USPAT;	2003/04/12 10 -
	1		US-PGPUB;	2003/04/12 10:3
			EPO; JPO;	
			DERWENT;	
	175	(("MFMS" and minner)	IBM TDB	
1	-,5	(("MEMS" and mirror) and cavity) and (substrate and sacrificial)	USPAT;	2003/04/12 10:4
	1	(Substitute and Sacrificial)	US-PGPUB;	10.4
			EPO; JPO;	
ļ			DERWENT;	
ļ	10114	variable adj capacitor	IBM_TDB	
ļ	I	J owbaction	USPAT;	2003/04/12 10:4
İ	İ		US-PGPUB;	
ſ	- 1		EPO; JPO;	
1			DERWENT;	
	224	"MEMS" and (variable adj capacitor)	IBM_TDB	0005 (0)
		capacitor)	USPAT;	2003/04/12 10:50
ſ			US-PGPUB;	
1	j		EPO; JPO;	
			DERWENT;	
	ry 4/1	2/03 3:57:11 PM Page 1	IBM TDB	

-	1	0 ("200100560618").PN.	USPAT;	12002/04/10 12
1	1		US-PGPUB;	2003/04/12 12:20
1	1		EPO; JPO;	
	1		DERWENT;	
1_			IBM TDB	
-] 2	("20010050618").PN.	USPAT;	0000 (5.1
	1		US-PGPUB;	2003/04/12 12:20
Í		•		
1			EPO; JPO;	' [
			DERWENT;	İ
-	7774	"shin-etsu"	IBM_TDB	ł
	l e		USPAT;	2003/04/12 12:57
			US-PGPUB;	1
	1		EPO; JPO;	
1			DERWENT;	I l
-	30719	wafer and hydrogen	IBM_TDB	1
		water and nydrogen	USPAT;	2003/04/12 12:58
	1		US-PGPUB;	==,55
İ	1		EPO; JPO;	1
1			DERWENT;	1
-	631	"ship-otes" and (c	IBM TDB	ļ
	031	"shin-etsu" and (wafer and hydrogen)	USPAT;	2003/04/12 12:58
	1		US-PGPUB;	12.38
	}		EPO; JPO;	1
			DERWENT;	1
Í -	1974	-41:	IBM TDB	1
1	19/4	stacking adj faults	USPAT:	2003/04/12 12:58
			US-PGPUB;	2003/04/12 12:58
ł			EPO; JPO;]
			DERWENT;	i !
l _	42		IBM TDB	
	42	("shin-etsu" and (wafer and hydrogen)) and	USPAT;	2003/04/12 13:10
		(stacking adj faults)	US-PGPUB;	2003/04/12 13:10
			EPO; JPO;	1
	1		DERWENT;]
	20070		IBM TDB	[]
_	326/641	vacuum or pressure	USPAT;	2002/01/12
			US-PGPUB;	2003/04/12 13:12
			EPO; JPO;	
	j			ł
			DERWENT;	
-	15	(("shin-etsu" and (wafer and hydrogen))	IBM_TDB	
]	and (stacking adj faults)) and (vacuum or	USPAT;	2003/04/12 13:12
]	pressure)	US-PGPUB;	i
			EPO; JPO;	ſ
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			IBM TDB	1